

Newly-Developed Tool for Thickness Measurement of Blanket Wafers

Metrology tool combining XRR and ED-XRF for film measurement

Film thickness monitor tool with low COO for 200 mm and smaller wafers

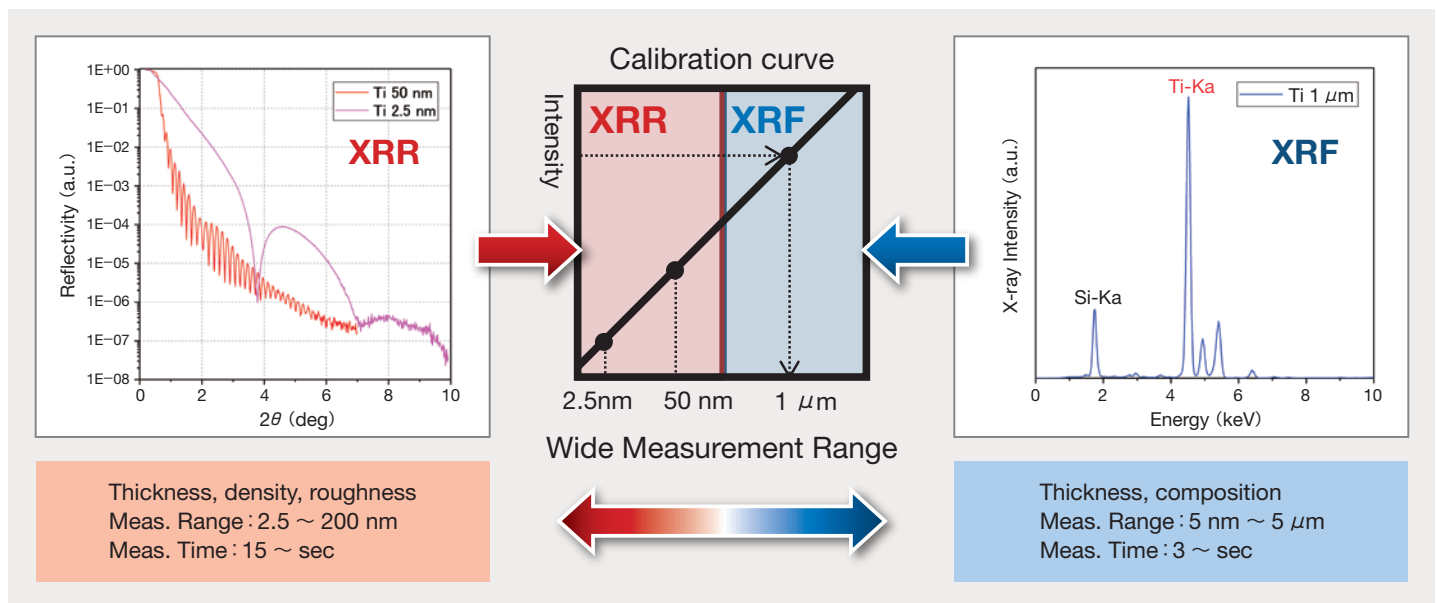
FEATURES

- X-ray reflectivity (XRR) and X-ray fluorescence (XRF) capability. Applicable to a wide range of thicknesses and film types without need to prepare standard samples.
- High throughput (TP > 30 w/h, depending on film type) and full-wafer measurement (with 3 mm edge exclusion).
- XRR: Wide dynamic range and high-throughput measurement with a high-performance X-ray detector.
- XRF: High-sensitivity analysis by a silicon drift detector (SDD), mapping measurement by a small X-ray beam spot, and stable elemental analysis (Al⁻) by a new optical system.



Applicable to a wide range of thicknesses from nm to μm order. Easy to analyze a wide variety of film types.

XHEMIS EX-2000



Many Applications

Barrier metal, Al/W wire, W process, Backside electrode, Oxide and nitride films